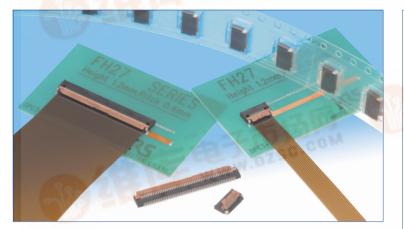
NEW 查询FH27-10S-0.4SH供应商

捷多邦,专业PCB打样工厂,24小时加急出货

0.4 mm Contact Pitch, 1.2 mm above the board, Flexible Printed Circuit ZIF Connectors

FH 27 Series



WW.DZSC

Overview

Continuous miniaturization of personal mobile devices created a need for a low profile, high density interconnection system.In the same time, the demand for higher currents and higher reliability Flexible Printed Circuits has also increased. Hirose meets all these challenges with introduction of this connector.

Features

1. Low profile, small PCB mounting area, weight reduction Protruding only 1.2 mm above the board the connector occupies 50% less area than comparable type having contacts spaced on 0.5 mm centers.

Creative design, coupled with high manufacturing capabilities resulted in extremely low weight of the connector.

- 2. Higher current carrying capacity Contact spacing of 0.4 mm allows production of wider and simpler pattern of conductive traces on FPC.
- 3. FPC temporary hold and verification of correct insertion The connector has built-in FPC hold protrusions allowing the tactile feel of the correct FPC insertion and holding it in position before closing of the actuator.

4. Uses standard 0.2 mm thick FPC

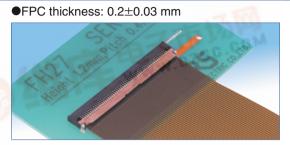
5. One-finger operation of the actuator

Proven (in several other Hirose's connectors!) Flip-Lock rotating actuator assures reliable mechanical and electrical connection with FPC, confirming it with a definite tactile feel.

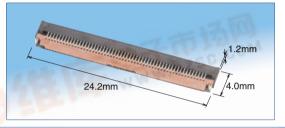
- 6. Board placement with automatic equipment Flat top surface and packaging on the tape-and reel allows the use of vacuum nozzles. Standard reel contains 2,500 connectors.
- 7. Environmental considerations The center cores of the embossed tape reels are made of Styrofoam.
- 8. Variety of contact positions Available with 10, 40, 54, 57 and 60 pos.

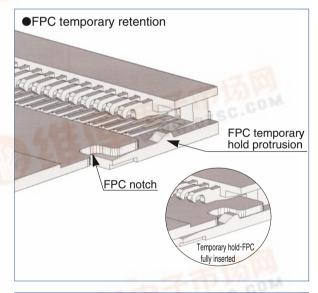
Applications

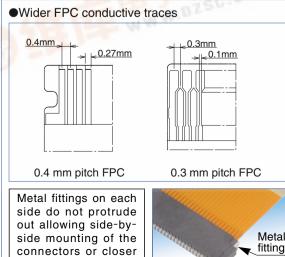
Mobile phones, PDA's, digital cameras, digital video cameras, LCD connections, plasma displays (PDP), camera modules and other compact devices requiring Flexible Printed Circuit connections using high reliability ultra-small



1.2 mm Height, actuator fully closed.(54 pos. shown)







component placement.

Product Specifications

Dating	Rated current 0.4 A DC	Operating temperature range -55℃ to +85℃ (Note 1)	Storage temperature range -10° C to $+50^{\circ}$ C (Note 2)
Rating	Rated voltage 40 V AC	Operating humidity range	Storage humidity range
		Relative humidity 90% max. (No condensation)	Relative humidity 90% max.

Recommended FPC Thickness: = 0.2±0.03mm tin-lead plated (Note 3)

Item	Specification	Conditions		
1. Insulation resistance	500 M Ω min.	100 V DC		
2. Withstanding voltage	No flashover or insulation breakdown.	120 V AC /one minute		
3. Contact resistance	100 m ohms max.	1 mA		
	* Including FPC conductor resistance			
4. Durability	Contact resistance: 100 m Ω max.	20 cycles		
(insertion/ withdrawal)	No damage, cracks, or parts dislocation.			
	No electrical discontinuity of 1 μ s or more.	Frequency 10 to 55 Up, single amplitude of 0.75 mm, 10 system		
5. Vibration	Contact resistance: 100 m Ω max.	Frequency: 10 to 55 Hz, single amplitude of 0.75 mm, 10 cycle in each of the 3 directions.		
	No damage, cracks, or parts dislocation.	each of the 3 directions.		
	No electrical discontinuity of 1 μ s. min.	Acceleration of 0.01 m/c^2 (ma duration size half wave		
6. Shock	Contact resistance: 100 m Ω max.	Acceleration of 981 m/s ² , 6ms duration, sine half-wave		
	No damage, cracks, or parts dislocation.	waveform, 3 cycles / each of 3 axis		
7. Humidity	Contact resistance: 100 m Ω max.			
,	Insulation resistance: 50 M Ω min.	96 hours at temperature of 40°C and humidity of 90% to 95%.RH		
(Steady state)	No damage, cracks, or parts dislocation.			
	Contact resistance: 100 m Ω max.	Temperature: -55° C $\rightarrow +15^{\circ}$ C to $+35^{\circ}$ C $\rightarrow +85^{\circ}$ C $\rightarrow +15^{\circ}$ C to $+35^{\circ}$ C		
8. Temperature cycle	Insulation resistance: 50 M Ω min.	Time: $30 \rightarrow 2$ to $3 \rightarrow 30 \rightarrow 2$ to 3 (Minutes)		
	No damage, cracks, or parts dislocation.	5 cycles		
9. Resistance to	No deformation of components offecting norfermance	Reflow: At the recommended temperature profile		
soldering heat	No deformation of components affecting performance.	Manual soldering: 350℃±5℃ for 5 seconds		

Note 1: Includes temperature rise caused by current flow.

Note 2: The term "storage" refers to products stored for long period of time prior to mounting and use. Operating Temperature Range and Humidity range covers non- conducting condition of installed connectors in storage, shipment or during transportation.

Note 3: When using FPC with gold plated contact pads the connector contacts must be also gold plated : Select the (05) plating code.

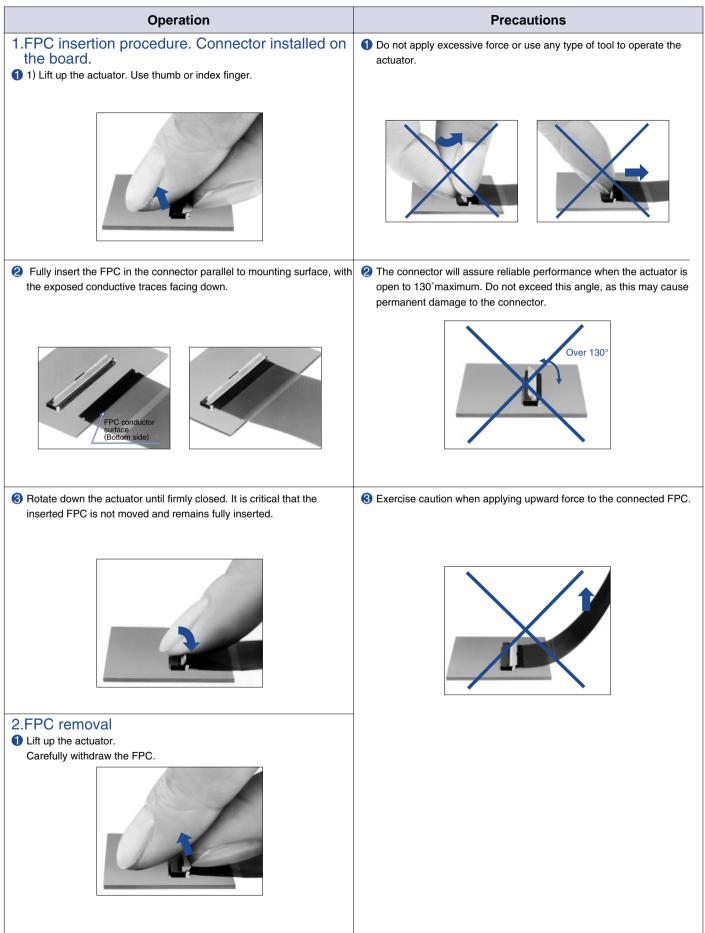
Materials

Part	Material	Finish	Remarks
Insulator	LCP	Color: Black	UL94V-0
Actuator	LCP	Color: Dark brown	
Contacts	Phosphor bronze	Tin-lead plated (Note 3)	
Metal fittings	Phosphor bronze	Tin plated(No-lead)	

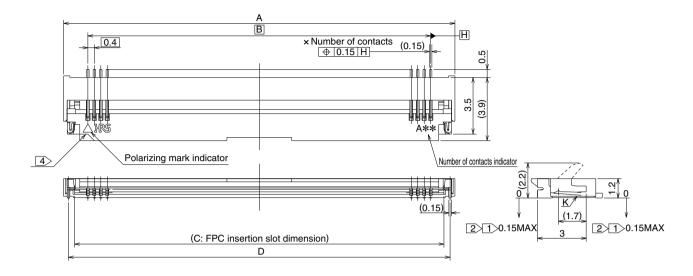
Ordering information

Fł	H27	- 54S	-0.4	- SH	(05)			
	0	2	3	4	6			
1	Series	name: FH2	7			4	Terminal type	
2	No. of	contacts					SH: SMT horizonta	al mounting type
	Numbe	er of contact	s: 10, 40,	54, 57, 6	60	6	Plating code	(05): Gold plated
8	Contac	ct pitch: 0.4	mm					(51): Tin-lead plated

Operation and Precautions



Connector Dimension



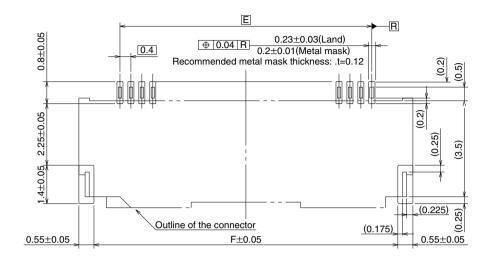
Notes $\boxed{1}$ The coplanarity of each terminal lead is within 0.1.

- $\boxed{2}$ The contact terminal lead position indicates the dimension from the K surface, the bottom surface of the insulator body.
- 3 Slight variations in color of the plastic compounds do not affect form, fit or function of the connector.
- $|4\rangle$ Some versions may have material removed from this area. No affect on form, fit or function of the connector.

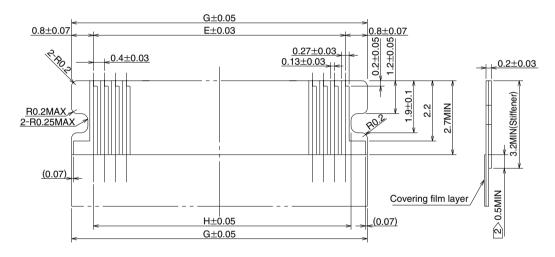
Part Number	CL No.	Number of Contacts	А	В	С	D
FH27-10S-0.4SH	CL580-0004-0	10	6.6	3.6	5.24	6.0
FH27-40S-0.4SH	CL580-0005-3	40	18.6	15.6	17.24	18.0
FH27-54S-0.4SH	CL580-0001-2	54	24.2	21.2	22.84	23.6
FH27-57S-0.4SH	CL580-0003-8	57	25.4	22.4	24.04	24.8
FH27-60S-0.4SH	CL580-0006-6	60	26.6	23.6	25.24	26.0

Tape and reel packaging (2,500 pieces/reel). Order by number of reels. Unit: mm

Recommended PCB mounting pattern and metal mask dimensions



Recommended FPC Dimensions



- 1 Polyamide and thermally hardening adhesive is recommended as the materials for the stiffener.
- $\boxed{2}$ Overlap between covering film layer and stiffener is 0.5mm min.

					ond nin
CL No.	Number of Contacts	E	F	G	Н
CL580-0004-0	10	3.6	5.5	5.2	4.01
CL580-0005-3	40	15.6	17.5	17.2	16.01
CL580-0001-2	54	21.2	23.1	22.8	21.61
CL580-0003-8	57	22.4	24.3	24.0	22.81
CL580-0006-6	60	23.6	25.5	25.2	24.01
	CL580-0004-0 CL580-0005-3 CL580-0001-2 CL580-0003-8	CL580-0004-0 10 CL580-0005-3 40 CL580-0001-2 54 CL580-0003-8 57	CL580-0004-0 10 3.6 CL580-0005-3 40 15.6 CL580-0001-2 54 21.2 CL580-0003-8 57 22.4	CL580-0004-0 10 3.6 5.5 CL580-0005-3 40 15.6 17.5 CL580-0001-2 54 21.2 23.1 CL580-0003-8 57 22.4 24.3	CL580-0004-0 10 3.6 5.5 5.2 CL580-0005-3 40 15.6 17.5 17.2 CL580-0001-2 54 21.2 23.1 22.8 CL580-0003-8 57 22.4 24.3 24.0

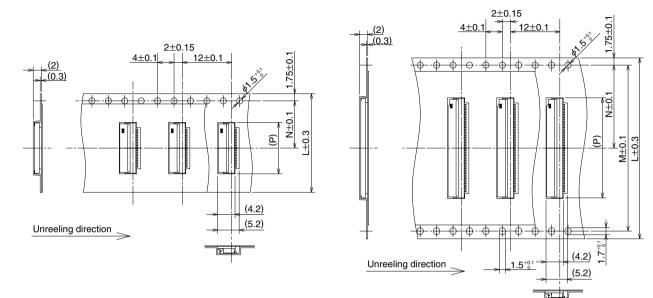
Unit: mm

Tape and tape reel packaging (2,500 pieces/reel). Order by number of reels.

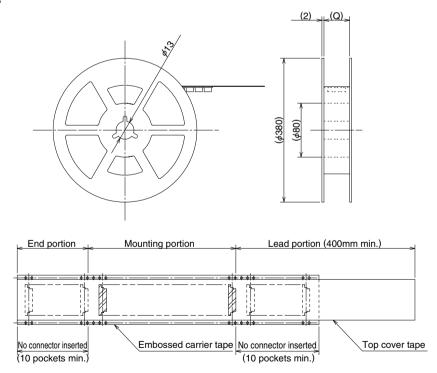
Packaging Specification Embossed Carrier Tape Dimensions

•Tape width up to 24mm .

•Tape width 32mm and over.



Reel Dimensions



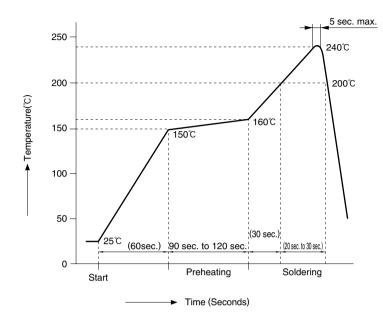
Unit:	mm

Part Number	CL No.	Number of Contacts	L	М	N	Р	Q
FH27-10S-0.4SH	CL580-0004-0	10	16.0		7.5	6.9	16.5
FH27-40S-0.4SH	CL580-0005-3	40	32.0	28.4	14.2	18.9	32.5
FH27-54S-0.4SH	CL580-0001-2	54	44.0	40.4	20.2	24.5	44.5
FH27-57S-0.4SH	CL580-0003-8	57	44.0	40.4	20.2	25.7	44.5
FH27-60S-0.4SH	CL580-0006-6	60	44.0	40.4	20.2	26.9	44.5

2,500 pieces per reel.

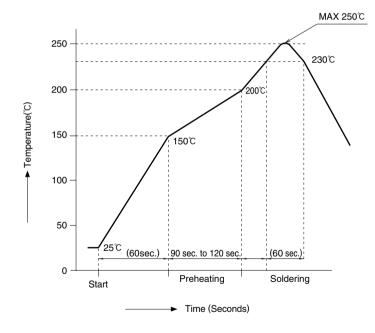
Recommended Temperature Profile

•Using Typical Solder Paste



HRS test conditions	
Solder method	:Reflow, IR/hot air
	(Nihon Den-netsu Co., Ltd.'s Part
	SENSBY NR-II)
Environment	:Room air
Solder composition	:Paste, 63%Sn/37%Pb
	(Senju Metal Industry, Co., Ltd.'s Part Number:
	OZ63-201C-50-9)
Test board	:Glass epoxy 40mm×100mm×1.6mm thick
	Land dimensions:0.23mm×0.8mm
Metal mask	:0.2×0.8×0.12mm thick

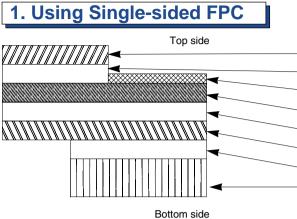
●Using Lead-free Solder Paste



HRS test condition	
Solder method	:Reflow, IR/hot air
	(Nihon Den-netsu Co., Ltd.'s Part Number:
	SENSBY NR- \mathbb{I})
Environment	:Room air
Solder composition	:Paste, 96.5%Sn/3.0%Ag/0.5%Cu
	(Senju Metal Industry, Co., Ltd.'s Part Number:
	M705-221CM5-42-10.5)
Test board	:Glass epoxy 70mm \times 80mm \times 1.6mm thick
	Land dimensions:0.23mm×08mm
Metal mask	:0.2×0.8×0.12mm thick

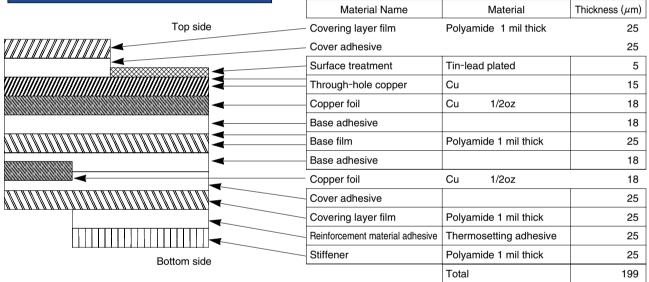
The temperature profiles shown are based on the above conditions. In individual applications the actual temperature may vary, depending on solder paste type, volume / thickness and board size / thickness. Consult your solder paste and equipment manufacturer for specific recommendations.

FPC Construction (Recommended Specifications)



			1
Ma	aterial Name	Material	Thickness (µm)
— Covering	layer film	Polyamide 1 mil thick.	25
— Cover ad	hesive		25
Surface t	reatment	Tin-lead plated	5
Copper fo	bil	Cu 1/2oz	35
Base adh	iesive		25
Base film		Polyamide 1 mil thick	25
Reinforcem	nent material adhesive	Thermosetting adhesive	30
Stiffener		Polyamide 3 mil thick	75
		Total	195

2. Using Double-sided FPC



To prevent release of the lock due to FPC bending, use of the FPC with copper foil on bottom side is not recommended.



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